

PACKAGE DIMENSIONS

DFN10, QFN24, QFN28, cQFN32, QFN48

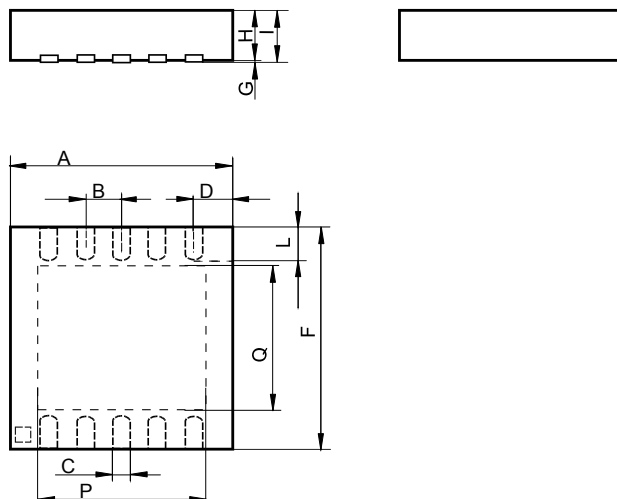


iC-Haus Application Guide

More Package Info

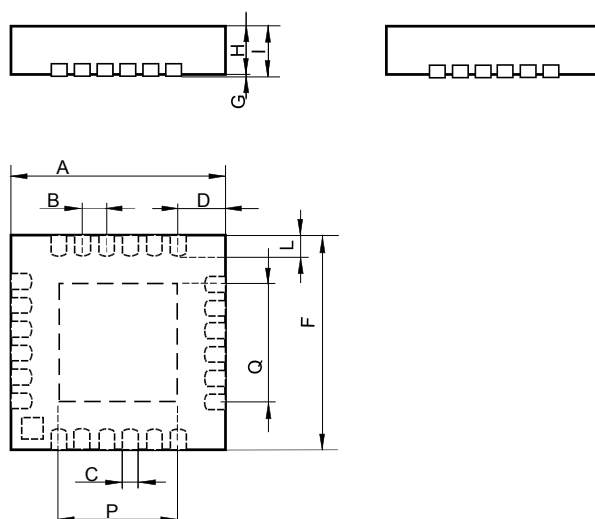
Release B2, Page 1/3

DFN10



[mm]		
	Min.	Max.
A	4.00	
B	0.65 BSC	
C	0.30	
D	0.7	
E	-	
F	4.00	
G	0	0.05
H	0.90	
I	0.80	1.00
L	0.40	
P	3.05	
Q	2.65	

QFN24



[mm]		
	Min.	Max.
A	4.00	
B	0.50	
C	0.18	0.30
D	0.75	
E	-	
F	4.00	
G	0	0.05
H	0.90	
I	0.80	1.00
L	0.30	0.50
P	2.30	2.55
Q	2.30	2.55

PACKAGE DIMENSIONS

DFN10, QFN24, QFN28, cQFN32, QFN48

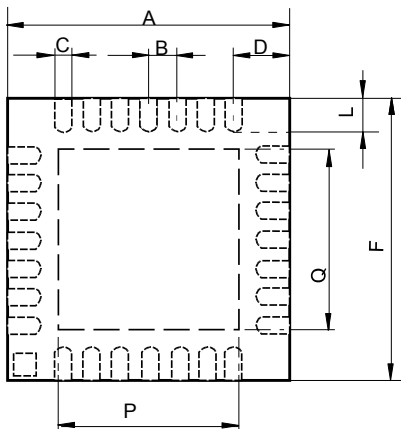
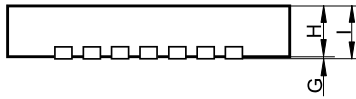


iC-Haus Application Guide

More Package Info

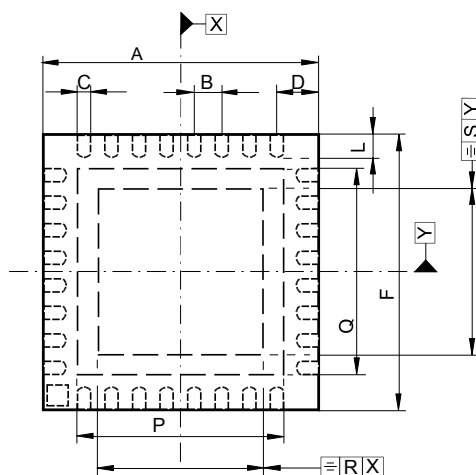
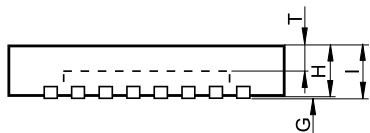
Release B2, Page 2/3

QFN28



[mm]		
	Min.	Max.
A	5.00	
B	0.50	
C	0.18	0.30
D	1.0	
E	-	
F	5.00	
G	0	0.05
H	0.90	
I	0.80	1.00
L	0.45	0.65
P	3.00	3.25
Q	3.00	3.25

cQFN32



[mm]		
	Min.	Max.
A	5.00	
B	0.50	
C	0.18	0.30
D	0.75	
F	5.00	
G	0	0.05
H	0.90	
I	0.80	1.00
L	0.30	0.50
P	3.75	
Q	3.75	
R	0.2*	
S	0.2*	
T	0.3*	0.6*
* chip placement		

PACKAGE DIMENSIONS

DFN10, QFN24, QFN28, cQFN32, QFN48

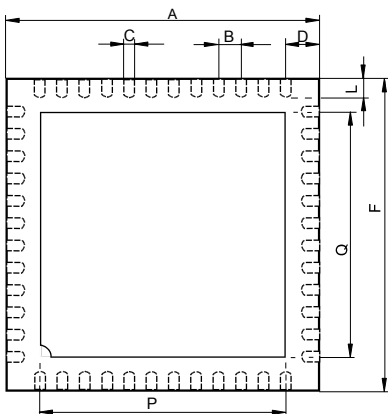
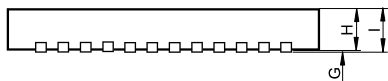


iC-Haus Application Guide

More Package Info

Release B2, Page 3/3

QFN48



[mm]		
	Min.	Max.
A	7.00	
B	0.50	
C	0.18	0.30
D	0.7	
F	7.00	
G	0	0.05
H	0.90	
I	0.80	1.00
L	0.3	0.5
P	5.8	
Q	5.4	5.65

For additional information on component handling, preconditioning and soldering conditions, refer to the relevant iC-Haus customer information files, available separately.